

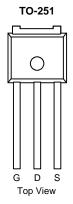
SW60N06V2-VB Datasheet N-Channel 60 V (D-S) 175 °C MOSFET

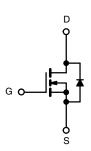
PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0050			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0055			
I _D (A)	97			
Configuration	Single			

FEATURES

- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- 100 % R_g and UIS Tested







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V_{DS}	60	V	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current	T _C = 25 °C	- I _D	97		
	T _C = 125 °C		56		
Continuous Source Current (Diode Conduction) ^a		Is	100	Α	
Pulsed Drain Current ^b		I _{DM}	290		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	45		
Single Pulse Avalanche Energy		E _{AS}	101	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	P _D	136	W	
	T _C = 125 °C	FD	45	V V	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	50	°C/W	
Junction-to-Case (Drain)		R_{thJC}	1.1	C/VV	

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.



PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static							,	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \mu A$		2.0	2.5	V	
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
		V _{GS} = 0 V	V _{DS} = 60 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = 60 V, T _J = 125 °C	-	-	50	μA	
		$V_{GS} = 0 V$	V _{DS} = 60 V, T _J = 175 °C	-	-	150		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	50	-	-	Α	
		V _{GS} = 10 V	I _D = 25 A	-	0.0050	-	Ω	
Drain Cauras On State Besistance	В	V _{GS} = 10 V	I _D = 25 A, T _J = 125 °C	-	0.0117	-		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 25 A, T _J = 175 °C	-	0.0149	-		
		V _{GS} = 4.5 V	I _D = 20 A	-	0.0055	-		
Forward Transconductanceb	9 _{fs}	V _{DS} = 15 V, I _D = 25 A		-	177	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}				4844	6060		
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 25 V, f = 1 MHz	-	441	555	pF	
Reverse Transfer Capacitance	C _{rss}]		-	200	250		
Total Gate Charge ^c	Qg			-	82	125		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_{D} = 50 \text{ A}$	-	14.5	-	nC	
Gate-Drain Charge ^c	Q _{gd}]		-	13.5	-		
Gate Resistance	R _g	f = 1 MHz		1	2	3	Ω	
Turn-On Delay Time ^c	t _{d(on)}				14	21		
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_L = 0.6 \Omega$ $I_D \cong 50 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		-	5	8	ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	41	62		
Fall Time ^c	t _f			-	7	11		
Source-Drain Diode Ratings and Chara	acteristics ^b							
Pulsed Current ^a	I _{SM}			-	-	290	Α	
Forward Voltage	V_{SD}	I _F = 50 A, V _{GS} = 0 V		-	0.9	1.5	V	

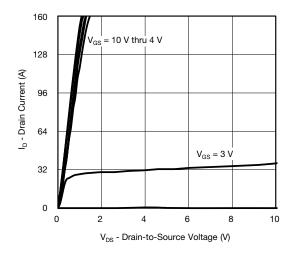
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

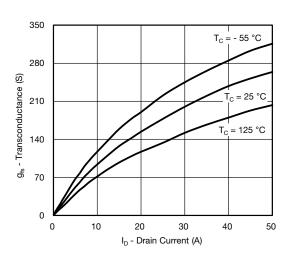
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



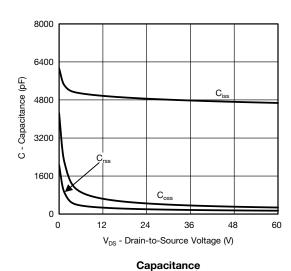
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



Output Characteristics



Transconductance



120
96
(£) T_C = 25 °C

T_C = 25 °C

T_C = - 55 °C

0

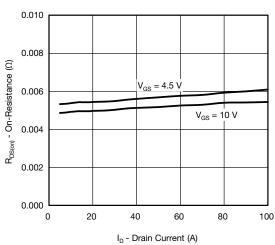
2

V_{GS} - Gate-to-Source Voltage (V) Transfer Characteristics

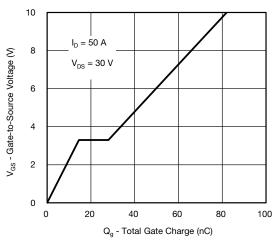
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8

10



On-Resistance vs. Drain Current



Gate Charge

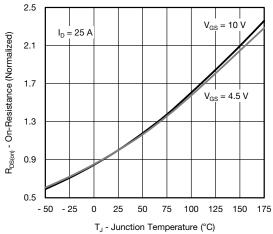


100 125 150 175

75

Drain Source Breakdown vs. Junction Temperature

TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



T_J - Junction Temperature (°C)

 $I_D = 1 \text{ mA}$

80

76

72

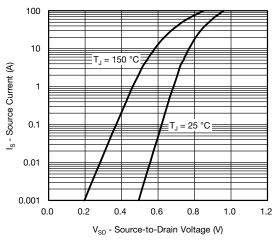
68

64

-50 -25 0 25 50

V_{DS} - Drain-to-Source Voltage (V)

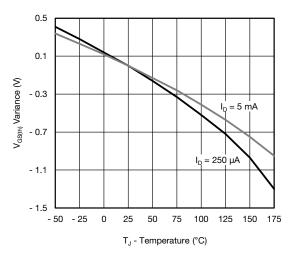




Source Drain Diode Forward Voltage

4



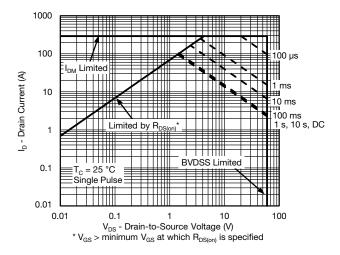


Threshold Voltage

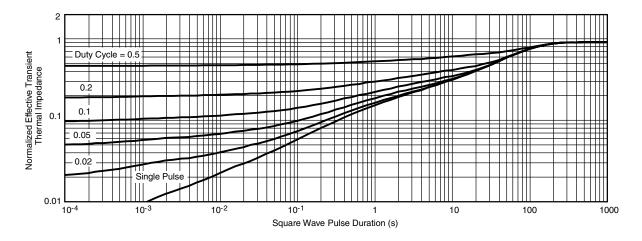


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THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



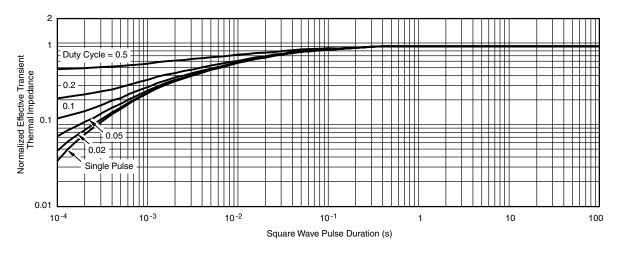
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

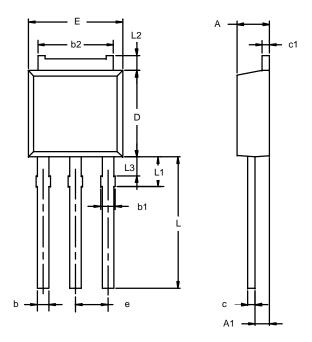
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-251AA



Note:	Dimension	L3 is for a	reference only.
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	MILLIM	IETERS	INC	HES
Dim	Min	Max	Min	Max
Α	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
С	0.46	0.58	0.018	0.023
с1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
Е	6.48	6.73	0.255	0.265
е	2.28 BSC		0.090	BSC
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060



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